



# IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

**In re Application of :**

Parthasarathy Rajagopalan  
Minh Vuong

**Serial No. :**

09/465,131

**Group Art Unit :**

2859

**Filed :**

December 16, 1999

**Examiner :**

Guadalupe, Yaritza

**For :**

Method and Apparatus for Thermal  
Profiling of Flip-Chip Packages

**Atty Docket :**

65611 / 99-099/RCE

I hereby certify that this correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, P. O. Box 1450, Alexandria, VA 22313-1450, on the date below:

Connie Del Castillo

8/16/05

Date

Connie Del Castillo

Signature

**SUBMISSION OF FORMAL DRAWINGS PURSUANT TO 37 C.F.R. §1.85**

**Official Draftsman**

Commissioner for Patents  
P. O. Box 1450  
Alexandria, VA 22313-1450

Sir:

Applicant hereby substitutes the enclosed formal drawings for those presently in the above referenced application.

LSI Logic Corporation  
1621 Barber Lane, MS D-106  
Milipitas, CA 95035  
408-433-7475

Date: 8/16/2005

Respectfully submitted,

Henry Groth

Henry Groth

Reg. No. 39,696